



# R&D Deposition Tool



**R & D**  
**PVD System**  
**Sputter Deposition**  
**Evaporation**

First developed by ESC back in 1999, this versatile deposition system is aimed at the research & development market. This flexible solution is easily configurable to meet the end users individual requirements.

[www.equipment-support.com](http://www.equipment-support.com)

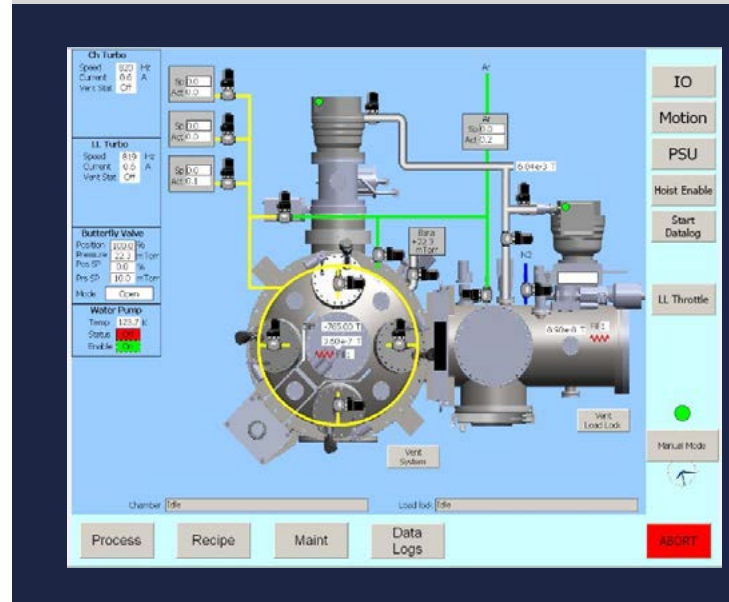
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## Deposition Chamber Options

- Downwards or upwards sputtering
- RF, DC or Pulsed DC sputtering
- Evaporation, thermal or E-beam
- Ion beam assisted deposition for either sputtering or evaporation
- Reactive sputtering
- In process monitoring
- Turbo pump or cryo pump
- Wide range of round cathode sizes 2" up to 8"
- Up to five process gases, either chamber fed or at the cathode
- Substrate holder up to 8" round
- Substrate rotation
- Substrate heating
- Substrate bias RF or DC

## Load Lock Options

- Low vacuum, backing pump only
- High vacuum, turbo pump or cryo pump
- Substrate RF etch
- Substrate heat
- Single substrate or multiple substrate
- Substrate holder up to 8" round



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